

FlexTech Alliance Awards Contract to Etched in Time for Linear Plasma Etch Module Used in Roll to Roll Manufacture

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System Specifically Designed for Plasma Etching Dielectric Films Required in Flexible Electronics Fabrication

SAN JOSE, Calif. -- The FlexTech Alliance, focused on developing the electronic display and the flexible, printed electronics industry supply chain, today announced the award of a contract to Etched in Time, Inc., totaling \$324,000. Under the contract, Etched in Time (EITI) will develop a linear plasma etch module using high density downstream processing in conjunction with reactive ion etch (RIE) for etching of dielectric films. In the emerging advanced flexible microelectronics industry, dry plasma etch is frequently desired over wet etch. At the end of the six-month contract, EITI's module will be incorporated into the Roll to Roll system at Binghamton University's Center for Advanced Microelectronics Manufacturing (CAMM) facility in Upstate New York.

This new-type of plasma source, S-type direct, developed by EITI, will provide plasma for a variety of uses - plasma clean, adhesion promotion, and PECVD. "There are currently no plasma sources for roll to roll offered with proven precise, reactive ion etch-grade, dry etch processes," stated Robert Henderson, president of EITI, in Tempe, Ariz. "Our innovative S-shape, RF discharge source, offers a number of manufacturing advantages for printed electronics, such as high density plasma for low power, low cost construction, compact design, scalable to any linear length, and high uniformity." The system is designed to be compatible with a range of roll to roll tools, offering a variety of companies in the industry the advantages obtainable through this new technology development.

"As one of the FlexTech project team leaders for Etched in Time, I'm pleased to see this critical requirement for flexible electronics fabrication addressed," noted Mark Poliks, director of research and development at Endicott Interconnect Technologies, Inc., (EI), as well as technical director for the CAMM. "We are looking forward to having the module installed at our facility, and proceeding with the follow-on work of refining the new process for different materials." Etched in Time brings over 25 years of experience in design and development of sputtering, resist coating and etch systems to this project.